Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: HPA 006 VDFN 7x5x0.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
•		"Contained In"	% Total			46.31	(mg) Total	Mold Compound	% ot Total Weight	56.27
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm		, 0,			
Silica, fused	60676-86-0	Mold Compound	50.643	41.679	506,430		Silica, fused	60676-86-0	90.00	
Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	Mold Compound Mold Compound	2.729 2.729	2.246 2.246	27,291 27,291		Epoxy Resin Phenolic Resin	Trade Secret Trade Secret	4.85 4.85	
Carbon Black	1333-86-4	Mold Compound	0.169	0.139	1.688		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	39.445	32.464	394.454		Cui bon Black	Total	100.00	
Iron	7439-89-6	Lead Frame	0.932	0.767	9.324	33.36	(mg) Total	Lead Frame	% of Total Weight	40.54
Zinc (Metal)	7440-66-0	Lead Frame	0.101	0.083	1.014	33.30	Copper	7440-50-8	97.30	40.04
Phosphorous	7723-14-0	Lead Frame	0.061	0.050	608		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.225	0.185	2,250		Zinc (Metal)	7440-66-0	0.25	
Methacrylic acid, isobornyl ester	7534-94-3	Die Attach	0.042	0.035	420		Phosphorous	7723-14-0	0.15	
1,3-Bismaleimidobenzene	3006-93-7	Die Attach	0.023	0.019	225			Total	100.00	
polymer with oxirane mono-2-propenoate	1017237-78-3	Die Attach	0.011	0.009	105	0.25	(mg) Total	Die Attach	% of Total Weight	0.30
Silicon	7440-21-3	Chip (Die)	1.460	1,202	14,600		Silver	7440-22-4	75.00	
Gold	7440-57-5	Wire Bond	0.250	0.206	2.500	M	ethacrylic acid, isobornyl es	7534-94-3	14.00	
Nickel	7440-02-0	Plating on external leads (pins)	1.112	0.915	11,118		1,3-Bismaleimidobenzene	3006-93-7	7.50	
Palladium	7440-05-3	Plating on external leads (pins)	0.043	0.035	426	polym	er with oxirane mono-2-prop	1017237-78-3	3.50	
Gold	7440-57-5	Plating on external leads (pins)	0.026	0.021	256			Total	100.00	
	7440-37-3	TOTALS:		82.300	1,000,000	1.20	Total (mg)	Chip (Die)	% of Total Weight	1.46
	0.0823	TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) &	100.000	82.300	1,000,000	1.20	Total (mg) Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	1.46
semiconductor device and its homogenous mat 863/EU (31 March 2015) and 2002/53/EC (End-of Diance with the above EU Directives has been v	0.0823 erials comply wit -Life Vehicles (El erified via interna	TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) & LV) without exemption (zero) al design controls, supplier declarations, and /or a	100.000 Directive 2011 analytical test d	82.300 /65/EU (08 Jul ata.	1,000,000 ne 2011) and	0.21	· · · · · · · · · · · · · · · · · · ·	7440-21-3	100.00	0.25
semiconductor device and its homogenous mat 863/EU (31 March 2015) and 2002/53/EC (End-of pliance with the above EU Directives has been v hemical substance is absent from the list above pochip Technology Incorporated's knowledge and	0.0823 erials comply wit -Life Vehicles (El erified via interna , the chemical su I belief as of the	TOTALS: g Total Mass h EU Directives: 2002/95/EC (27 January 2003) & -V) without exemption (zero)	100.000 Directive 2011 analytical test demiconductor dente to believe that	82.300 /65/EU (08 Jule ata. evice and, to the unavoidab	1,000,000 ne 2011) and ne best of	-	Doped Silicon	7440-21-3 Total	100.00 100.00	·
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Au 15:00 : 04/18/16